

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|--|-----------------|---------------|-------------------------|----------------|
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01 | 100.0 | 0.26 |
| | | | Subtotal | 0.01 | 100 | 0.26 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.23 | 100.0 | 5.2 |
| | | | Subtotal | 0.23 | 100 | 5.2 |
| Solder Wire | Tin alloy | Tin (Sn) | 7440-31-5 | 0 | 90.0 | 0.02 |
| | Tin alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0 | 0.5 | 0 |
| | Tin alloy | Silver (Ag) | 7440-22-4 | 0 | 2.5 | 0 |
| | Tin alloy | Antimony (Sb) | 7440-36-0 | 0 | 7.0 | 0 |
| | | | Subtotal | 0 | 100 | 0.02 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.18 | 100.0 | 4 |
| | | | Subtotal | 0.18 | 100 | 4 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 0.66 | 100.0 | 15 |
| | | | Subtotal | 0.66 | 100 | 15 |
| Heat Spreader | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.02 | 0.03 | 0.36 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.06 | 0.11 | 1.34 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 53.37 | 99.86 | 1213.3 |
| | | | Subtotal | 53.45 | 100 | 1215 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0 | 0.03 | 0.1 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.02 | 0.11 | 0.37 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 14.58 | 99.84 | 331.47 |
| | Copper alloy | Silver (Ag) | 7440-22-4 | 0 | 0.02 | 0.07 |
| | | | Subtotal | 14.6 | 100 | 332.01 |
| Mould Compound | | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 0.18 | 0.7 | 4.04 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 1.52 | 6.0 | 34.62 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.05 | 12.0 | 69.24 |
| | Filler | Silica fused | 60676-86-0 | 17.77 | 70.0 | 403.9 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.08 | 0.3 | 1.73 |
| | Filler | Misc. Silica compounds (generic) | 14808-60-7 | 2.54 | 10.0 | 57.7 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 0.25 | 1.0 | 5.77 |
| | | | Subtotal | 25.39 | 100 | 577 |
| Isolator | Copper alloy | Phosphorous (P) | 7723-14-0 | 0 | 0.1 | 0.1 |
| | Copper alloy | Aluminium Trioxide (Al2O3) | 1344-28-1 | 3.83 | 91.6 | 87.02 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.04 | 0.9 | 0.85 |
| | Copper alloy | Molybdenum (Mo) | 7439-98-7 | 0.29 | 7.0 | 6.65 |
| | Copper alloy | Manganese (Mn) | 7439-96-5 | 0.02 | 0.4 | 0.38 |
| | | | Subtotal | 4.18 | 100 | 95 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.07 | 5.0 | 1.5 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.03 | 2.5 | 0.75 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 1.22 | 92.5 | 27.75 |
| | | | Subtotal | 1.32 | 100 | 30 |
| | | | Total | 100.02 | 100 | 2273.49 |

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.